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## **ULTRATECH RECEIVES ORDER FROM TAIWAN'S LARGEST LED CHIP MANUFACTURER**

### **Lithography System Order for Use in Customer Development for HBLED Manufacturing With Commitment to Purchase Several Additional Sapphire Lithography Systems**

SAN JOSE, Calif.—February 23, 2010—Ultratech, Inc. (NasdaqGM: UTEK), a leading supplier of lithography and laser-processing systems used to manufacture semiconductor devices, today announced that it has received an order from Taiwan's largest light-emitting diode (LED) chip manufacturer for an LED lithography system, which is specifically designed and optimized for high-brightness LED (HBLED) manufacturing. In addition, this customer has provided a conditional commitment to purchase several additional Sapphire 100 systems to meet its ramp requirements over the next few quarters. The Sapphire 100 tool is scheduled to be available for volume shipments in the second half of 2010.

According to a representative of the Taiwan-based company, the Sapphire 100 lithography system provides the high-economic value and advanced technology required for HBLED manufacturing. Upon the successful integration of the first Sapphire 100 into its manufacturing line, the additional systems will be used to support the company's HBLED capacity expansion plans.

"This strong commitment from a top-tier Taiwan customer reinforces the value Ultratech's new Sapphire 100 system provides to HBLED manufacturers," explained Doug Anberg, Ultratech's vice president of advanced stepper technology. "HBLEDs are expected to see strong growth over the next few years as they become increasingly integrated into the products we use in our everyday life. Ultratech's systems are specifically designed to provide cost-of-ownership advantages for leading HBLED manufacturing facilities around the world. We look forward to working closely with our Taiwan-based partner and all of our global customers as we continue to develop solutions designed to address the requirements for cost-effective HBLED manufacturing."

#### **Sapphire 100 Lithography System**

Building upon the cost and performance advantages of the highly reliable 1500 platform, the Sapphire 100 system offers the added advantage of Ultratech's patented Machine Vision System (MVS). The MVS delivers alignment flexibility that has significant advantages over standard alignment techniques. The Sapphire 100 was specifically designed to meet the wide range of lithography needs for the HBLED manufacturing industry.

Certain of the statements contained herein, which are not historical facts and which can generally be identified by words such as “anticipates,” “expects,” “intends,” “will,” “could,” “believes,” “estimates,” “continue,” and similar expressions, are forward-looking statements under Section 27A of the Securities Act of 1933, as amended, and Section 21E of the Securities Exchange Act of 1934, as amended, that involve risks and uncertainties, such as risks related to timing, delays, deferrals and cancellations of orders by customers, including as a result of semiconductor manufacturing capacity as well as our customers’ financial condition and demand for semiconductors; cyclicalities in the semiconductor and nanotechnology industries; general economic and financial market conditions including impact on capital spending, as well as difficulty in predicting changes in such conditions; rapid technological change and the importance of timely product introductions; customer concentration; our dependence on new product introductions and market acceptance of new products and enhanced versions of our existing products; lengthy sales cycles, including the timing of system installations and acceptances; lengthy and costly development cycles for laser-processing and lithography technologies and applications; integration, development and associated expenses of the laser processing operation; pricing pressures and product discounts; high degree of industry competition; intellectual property matters; changes in pricing by us, our competitors or suppliers; international sales; timing of new product announcements and releases by us or our competitors; ability to volume produce systems and meet customer requirements; sole or limited sources of supply; effect of capital market fluctuations on our investment portfolio; ability and resulting costs to attract or retain sufficient personnel to achieve our targets for a particular period; dilutive effect of employee stock option grants on net income per share, which is largely dependent upon our achieving and maintaining profitability and the market price of our stock; mix of products sold; outcome of litigation; manufacturing variances and production levels; timing and degree of success of technologies licensed to outside parties; product concentration and lack of product revenue diversification; inventory obsolescence; asset impairment; changes to financial accounting standards; effects of certain anti-takeover provisions; future acquisitions; volatility of stock price; foreign government regulations and restrictions; business interruptions due to natural disasters or utility failures; environmental regulations; and any adverse effects of terrorist attacks in the United States or elsewhere, or government responses thereto, or military actions in Iraq, Afghanistan and elsewhere, on the economy, in general, or on our business in particular. Such risks and uncertainties are described in Ultratech’s SEC reports including its Annual Report on Form 10-K filed for the year ended December 31, 2008 and Quarterly Report on Form 10Q for the quarter ended October 3, 2009. Due to these and additional factors, the statements, historical results and percentage relationships set forth herein are not necessarily indicative of the results of operations for any future period. These forward-looking statements are based on management’s current beliefs and expectations, some or all of which may prove to be inaccurate, and which may change. We undertake no obligation to revise or update any forward-looking statements to affect any event or circumstance that may arise after the date of this release.

**About Ultratech:** Ultratech, Inc. (NasdaqGM: UTEK) designs, manufactures and markets photolithography and laser processing equipment. Founded in 1979, the company's market-leading advanced lithography products deliver high throughput and production yields at a low, overall cost of ownership for bump packaging of integrated circuits and high-brightness LEDs. A pioneer of laser processing, Ultratech developed laser spike anneal technology, which increases device yield, improves transistor performance and enables the progression of Moore’s Law for 65-nm and below production of state-of-the-art consumer electronics. Visit Ultratech online at: [www.ultratech.com](http://www.ultratech.com).

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